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(54) Title: SOLDERABLE TRANSISTOR CLIP AND HEAT SINK

(57) Abstract

A clip or frame (10) secures a heat sink (12) having a slot (11) with grooves on opposing sides thereof to a transistor (22). The frame (10) has sides with a width therebetween which can be wedged into grooves on opposing sides of a slot (11) in the heat sink (12). A portion of the frame (10) is raised up between two parallel cuts in the frame (10). A transistor (22) is wedged under the raised up portion (44). The clip has legs (32, 34) which are insertable into a printed circuit board (35) for easy assembly of a heat sink (12), transistor (22), clip (10) and printed circuit board (35).

